WHAT IS CLAIMED IS:

1. A carrier plate removing method of removing a carrier plate from a workpiece disposed on a front surface of the carrier plate with a provisional bond layer interposed between the carrier plate and the workpiece, the carrier plate removing method comprising:

a first holding step of holding the carrier plate by a first holding unit and exposing the workpiece;

a stepped portion forming step of forming a stepped portion in which a back surface side projects outward of a front surface side at an outer peripheral edge of the carrier plate by processing the carrier plate from the workpiece side along the outer peripheral edge of the carrier plate after performing the first holding step;

a second holding step of holding the workpiece by a second holding unit and exposing the carrier plate after performing the stepped portion forming step; and

a carrier plate removing step of removing the carrier plate from the workpiece by applying a force to the stepped portion and moving the carrier plate in a direction of being separated from the workpiece by a removing unit after performing the second holding step.

2. The carrier plate removing method according to claim 1, wherein

in the carrier plate removing step, a fluid is blown between the workpiece and the carrier plate while the force is applied to the stepped portion by the removing unit.